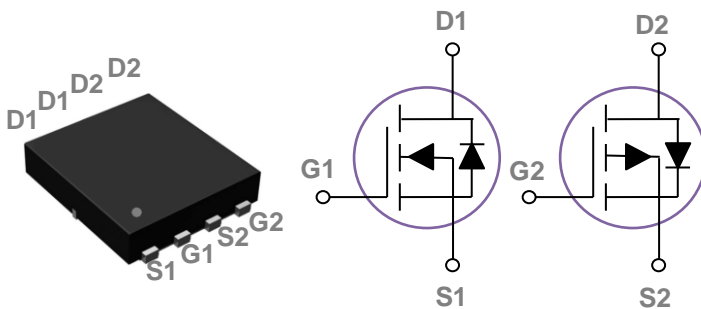


### General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK5x6 Dual Pin Configuration



BVDSS	RDSON	ID
40V	11.5mΩ	42A
-40V	30mΩ	-27A

### Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications
- 100% EAS Guaranteed

### Applications

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating		Units
$V_{DS}$	Drain-Source Voltage	40	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	42	-27	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	26.5	-17	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	168	-108	A
EAS	Single Pulse Avalanche Energy <sup>2,6</sup>	45	51	mJ
IAS	Single Pulse Avalanched Current <sup>2</sup>	30	32	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	34.7		W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.28		W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150		$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150		$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	3.6	$^\circ\text{C/W}$

**N-CH Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	40	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.04	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =15A	---	9.7	11.5	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =12A	---	12.5	16	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.6	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-4.9	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =3A	---	6	---	S

**Dynamic and switching Characteristics**

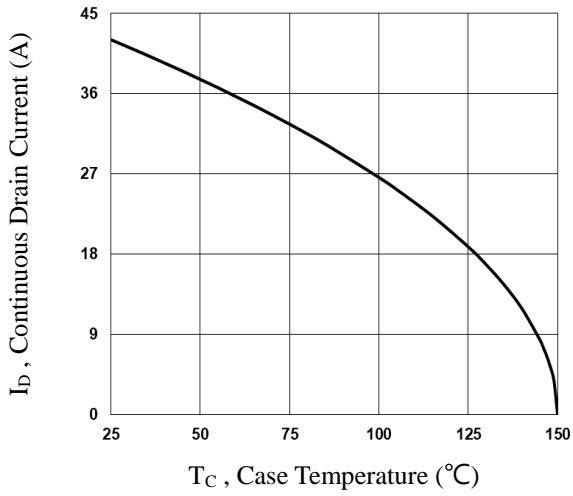
Q <sub>g</sub>	Total Gate Charge <sup>3, 4</sup>	V <sub>DS</sub> =20V, V <sub>GS</sub> =10V, I <sub>D</sub> =10A	---	16.9	32	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>3, 4</sup>		---	2	4	
Q <sub>gd</sub>	Gate-Drain Charge <sup>3, 4</sup>		---	4.4	9	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3, 4</sup>	V <sub>DD</sub> =20V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω I <sub>D</sub> =1A	---	8	16	ns
T <sub>r</sub>	Rise Time <sup>3, 4</sup>		---	3.2	8	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3, 4</sup>		---	26.4	52	
T <sub>f</sub>	Fall Time <sup>3, 4</sup>		---	3.8	8	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, F=1MHz	---	1109	2200	pF
C <sub>oss</sub>	Output Capacitance		---	114	220	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	89	180	
R <sub>g</sub>	Gate resistance		V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	2.8	

**Drain-Source Diode Characteristics and Maximum Ratings**

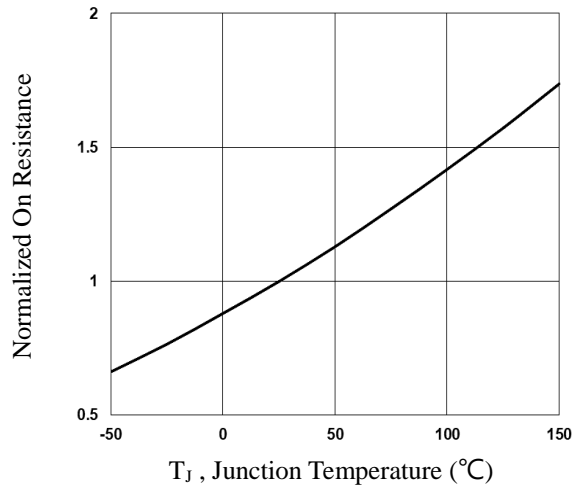
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	42	A
I <sub>SM</sub>	Pulsed Source Current		---	---	84	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V

Note :

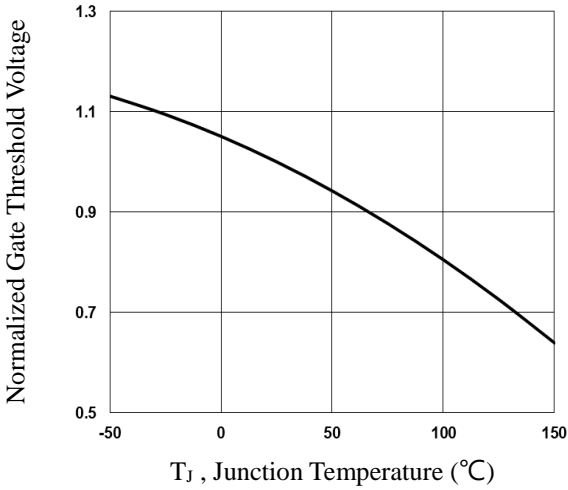
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=30A., R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



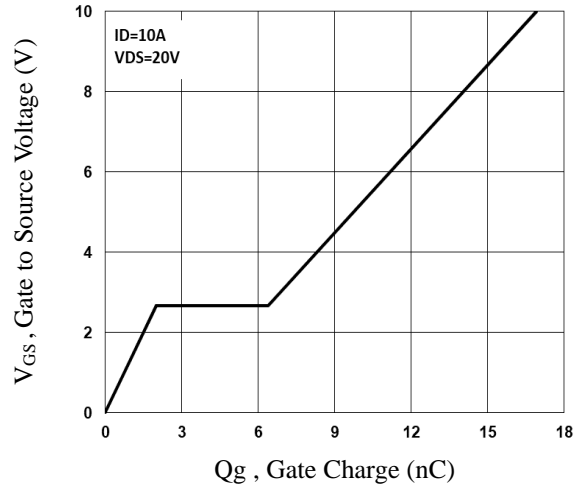
**Fig.1 Continuous Drain Current vs.  $T_C$**



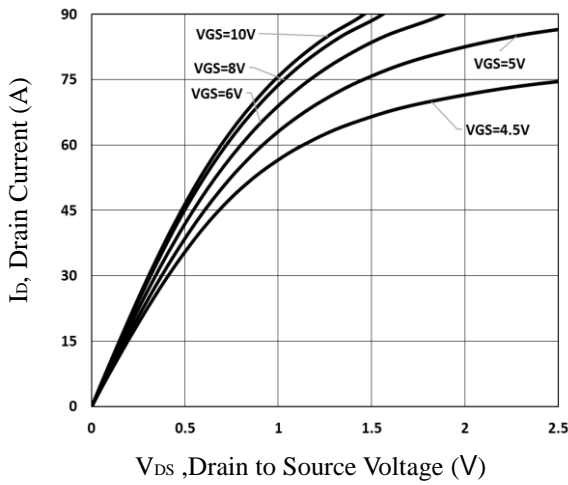
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



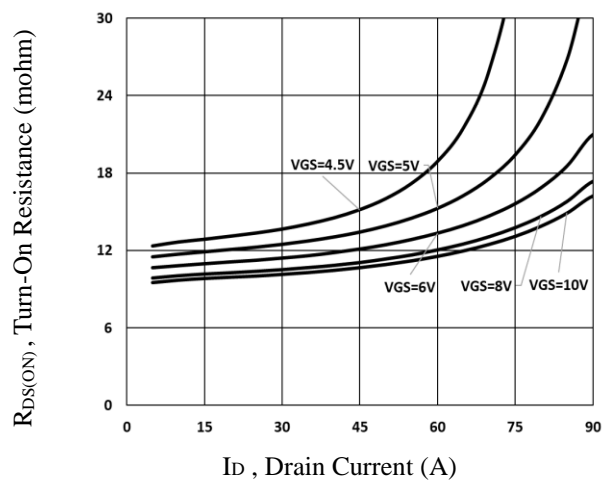
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



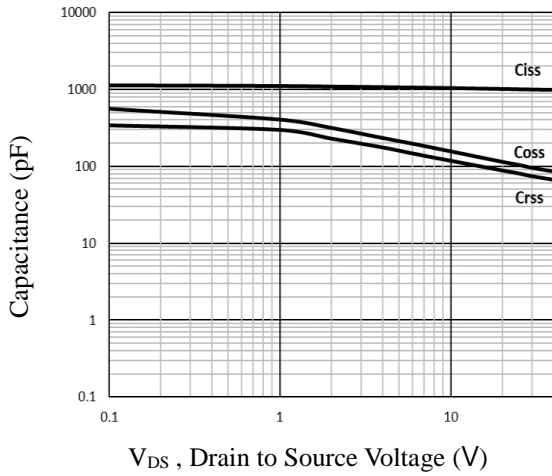
**Fig.4 Gate Charge Waveform**



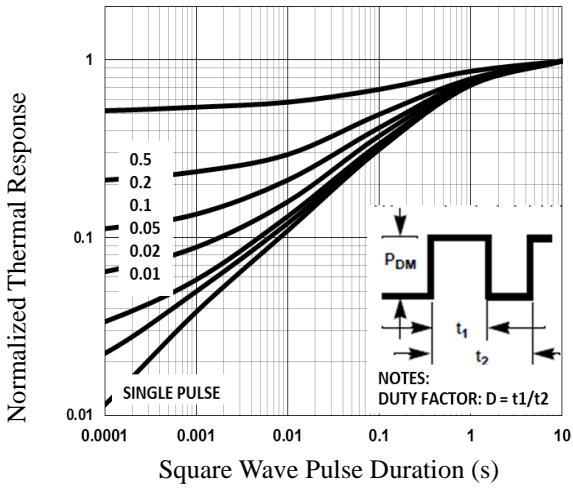
**Fig.5 Typical Output Characteristics**



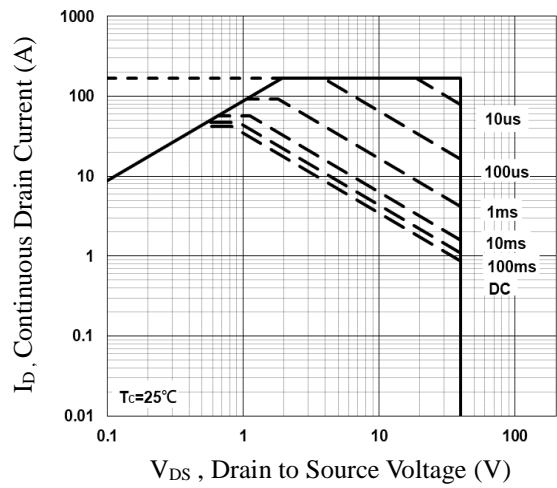
**Fig.6 Turn-On Resistance vs.  $I_D$**



**Fig.7 Capacitance Characteristics**



**Fig.8 Normalized Transient Response**



**Fig.9 Maximum Safe Operation Area**

**P-CH Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-40	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	---	0.02	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-32V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	-10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	---	25	30	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A	---	35	45	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.2	-1.5	-2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-4.4	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>D</sub> =-3A	---	6	---	S

**Dynamic and switching Characteristics**

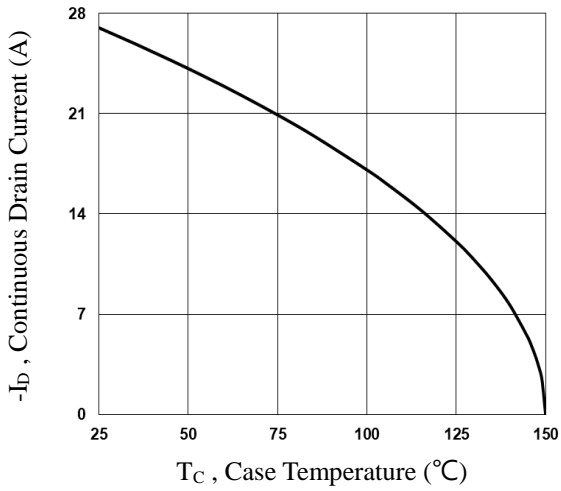
Q <sub>g</sub>	Total Gate Charge <sup>7,8</sup>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	---	23.2	46	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>7,8</sup>		---	2.9	6	
Q <sub>gd</sub>	Gate-Drain Charge <sup>7,8</sup>		---	4.3	8.6	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>7,8</sup>	V <sub>DD</sub> =-20V, V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω I <sub>D</sub> =-1A	---	12.8	25	ns
T <sub>r</sub>	Rise Time <sup>7,8</sup>		---	8.7	18	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>7,8</sup>		---	65	120	
T <sub>f</sub>	Fall Time <sup>7,8</sup>		---	12.6	25	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, F=1MHz	---	1320	2600	pF
C <sub>oss</sub>	Output Capacitance		---	116	230	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	89	180	

**Drain-Source Diode Characteristics and Maximum Ratings**

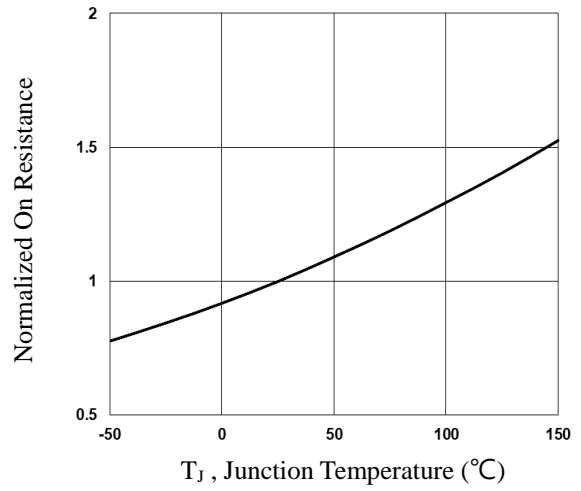
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-27	A
I <sub>SM</sub>	Pulsed Source Current		---	---	-54	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1	V

Note :

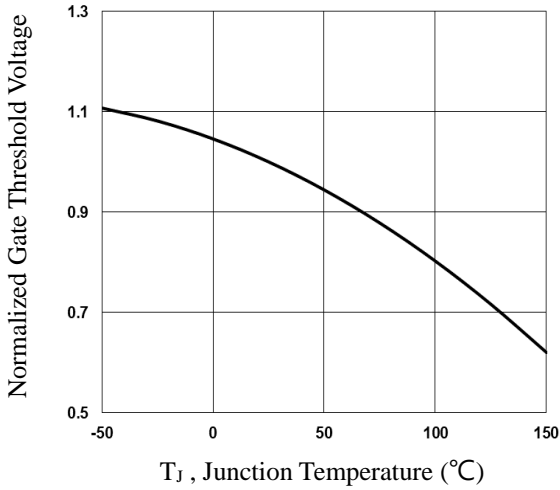
5. Repetitive Rating : Pulsed width limited by maximum junction temperature.
6. V<sub>DD</sub>=-25V, V<sub>GS</sub>=-10V, L=0.1mH, I<sub>AS</sub>=-32A., R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C
7. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
8. Essentially independent of operating temperature.



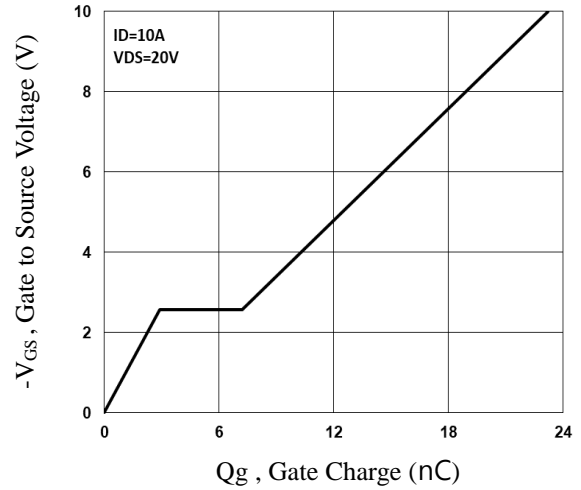
**Fig.10 Continuous Drain Current vs.  $T_c$**



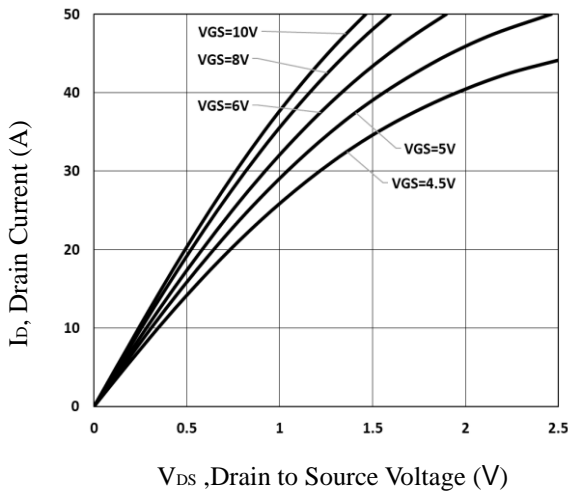
**Fig.11 Normalized  $R_{DS(on)}$  vs.  $T_j$**



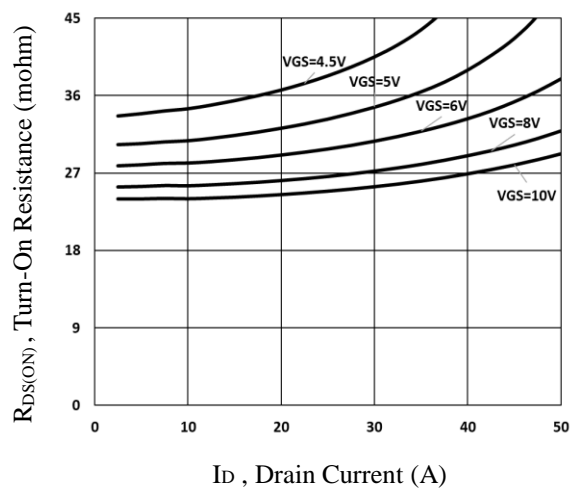
**Fig.12 Normalized  $V_{th}$  vs.  $T_j$**



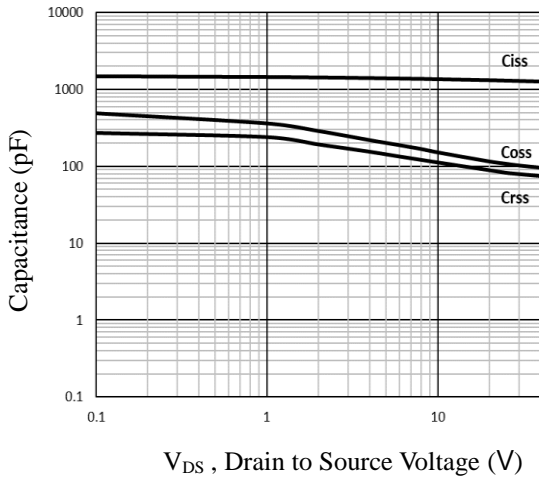
**Fig.13 Gate Charge Waveform**



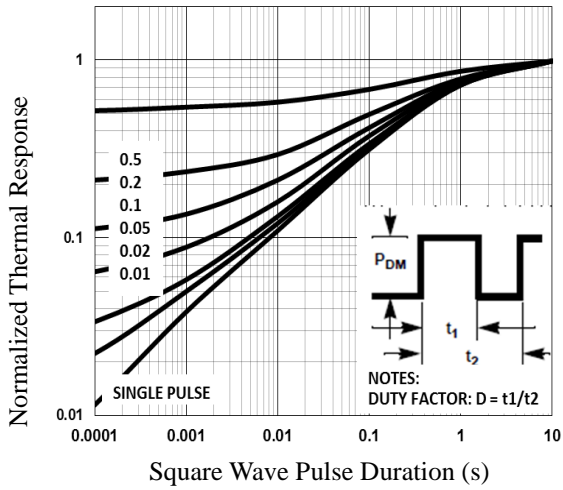
**Fig.14 Typical Output Characteristics**



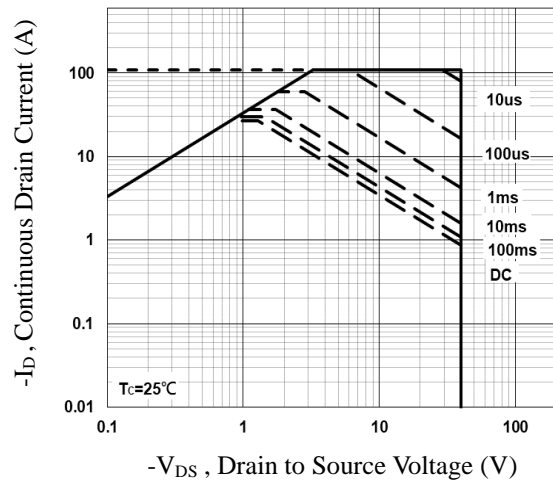
**Fig.15 Turn-On Resistance vs.  $I_d$**



**Fig.16 Capacitance Characteristics**

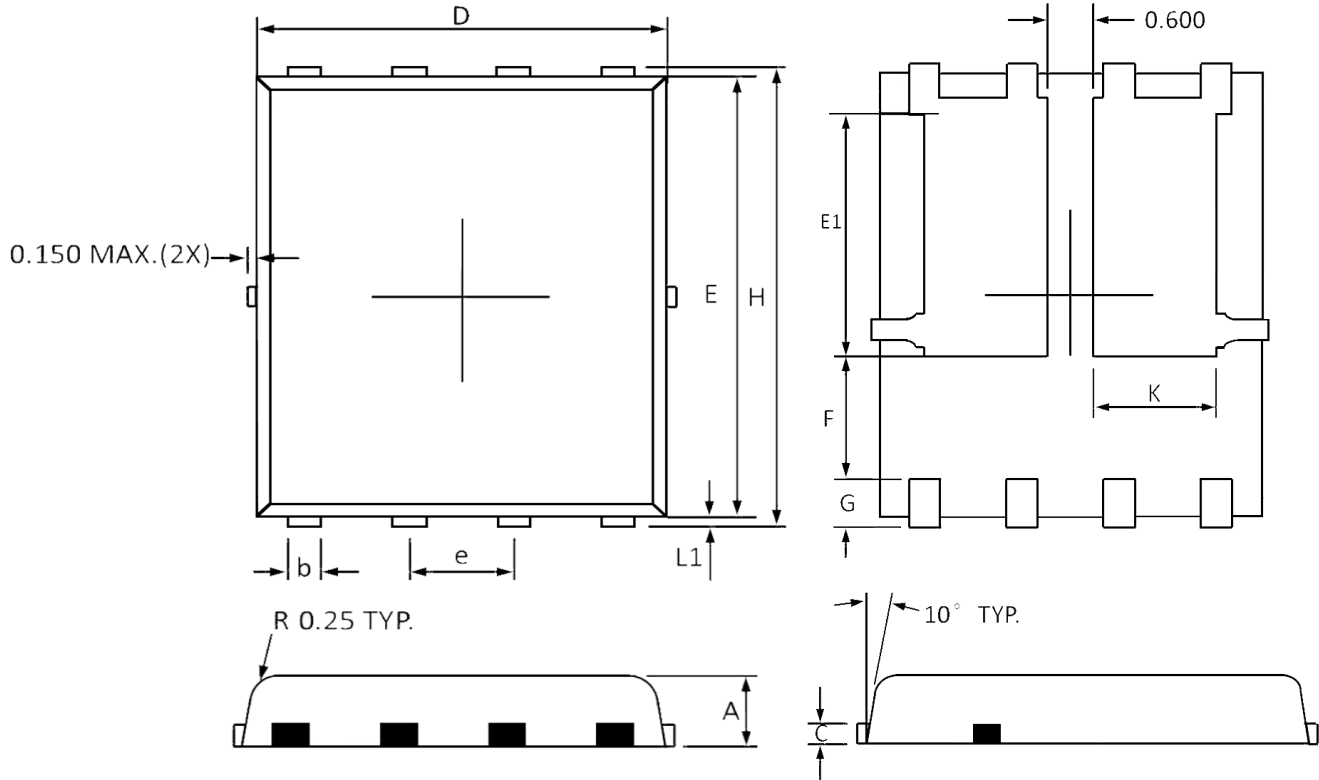


**Fig.17 Normalized Transient Impedance**



**Fig.18 Maximum Safe Operation Area**

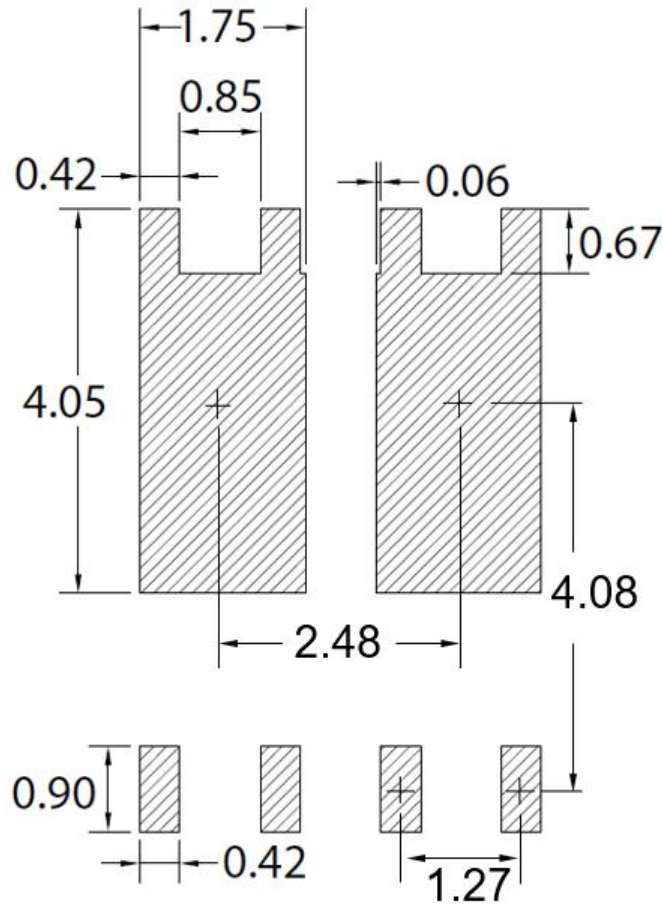
**PPAK5x6 Dual PACKAGE INFORMATION**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.200	0.031	0.047
b	0.300	0.510	0.012	0.020
C	0.250 Ref		0.010 Ref	
D	4.800	5.400	0.189	0.213
E	5.450	5.960	0.215	0.235
E1	3.200	3.800	0.126	0.150
e	1.27 BSC		0.050 BSC	
F	1.000	1.900	0.039	0.075
G	0.380	0.800	0.015	0.031
H	5.850	6.300	0.230	0.248
L1	0.050	0.250	0.002	0.010
K	1.500	1.900	0.059	0.074



PPAK5X6 Dual RECOMMENDED LAND PATTERN



unit : mm